

# FDP10N60NZ / FDPF10N60NZ

## N-Channel UniFET™ II MOSFET

600 V, 10 A, 750 mΩ

### Features

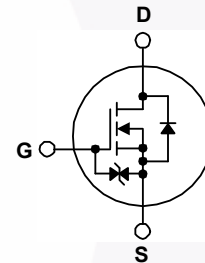
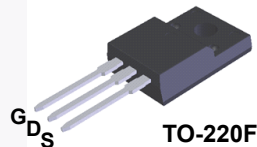
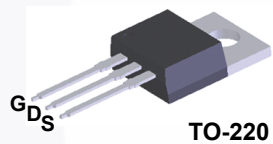
- $R_{DS(on)} = 640 \text{ m}\Omega$  (Typ.) @  $V_{GS} = 10 \text{ V}$ ,  $I_D = 5 \text{ A}$
- Low Gate Charge (Typ. 23 nC)
- Low  $C_{rss}$  (Typ. 10 pF)
- 100% Avalanche Tested
- Improved dv/dt Capability
- ESD Improved Capability
- RoHS Compliant

### Applications

- LCD/ LED/ PDP TV
- Lighting
- Uninterruptible Power Supply

### Description

UniFET™ II MOSFET is Fairchild Semiconductor's high voltage MOSFET family based on advanced planar stripe and DMOS technology. This advanced MOSFET family has the smallest on-state resistance among the planar MOSFET, and also provides superior switching performance and higher avalanche energy strength. In addition, internal gate-source ESD diode allows UniFET II MOSFET to withstand over 2kV HBM surge stress. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.



### MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	FDP10N60NZ	FDPF10N60NZ	Unit	
$V_{DSS}$	Drain to Source Voltage	600		V	
$V_{GSS}$	Gate to Source Voltage	±25		V	
$I_D$	Drain Current	- Continuous ( $T_C = 25^\circ\text{C}$ )	10	10*	A
		- Continuous ( $T_C = 100^\circ\text{C}$ )	6	6*	
$I_{DM}$	Drain Current	- Pulsed (Note 1)		A	
$E_{AS}$	Single Pulsed Avalanche Energy	(Note 2)		mJ	
$I_{AR}$	Avalanche Current	(Note 1)		A	
$E_{AR}$	Repetitive Avalanche Energy	(Note 1)		mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)		V/ns	
$P_D$	Power Dissipation	( $T_C = 25^\circ\text{C}$ )	185	38	W
		- Derate Above $25^\circ\text{C}$	1.5	0.3	
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150		°C	
$T_L$	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds	300		°C	

\*Drain current limited by maximum junction temperature.

### Thermal Characteristics

Symbol	Parameter	FDP10N60NZ	FDPF10N60NZ	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.68	3.3	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	62.5	

## Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FDP10N60NZ	FDP10N60NZ	TO-220	Tube	N/A	N/A	50 units
FDPF10N60NZ	FDPF10N60NZ	TO-220F	Tube	N/A	N/A	50 units

## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
--------	-----------	-----------------	------	------	------	------

### Off Characteristics

$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250 \mu\text{A}$ , $V_{GS} = 0 \text{ V}$ , $T_J = 25^\circ\text{C}$	600	-	-	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$ , Referenced to $25^\circ\text{C}$	-	0.6	-	$\text{V}/^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 600 \text{ V}$ , $V_{GS} = 0 \text{ V}$	-	-	1	$\mu\text{A}$
		$V_{DS} = 480 \text{ V}$ , $T_C = 125^\circ\text{C}$	-	-	10	
$I_{GSS}$	Gate to Body Leakage Current	$V_{GS} = \pm 25 \text{ V}$ , $V_{DS} = 0 \text{ V}$	-	-	$\pm 10$	$\mu\text{A}$

### On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 250 \mu\text{A}$	3.0	-	5.0	V
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}$ , $I_D = 5 \text{ A}$	-	0.64	0.75	$\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = 20 \text{ V}$ , $I_D = 5 \text{ A}$	-	14	-	S

### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = 25 \text{ V}$ , $V_{GS} = 0 \text{ V}$ , $f = 1 \text{ MHz}$	-	1110	1475	pF
$C_{oss}$	Output Capacitance		-	130	175	pF
$C_{riss}$	Reverse Transfer Capacitance		-	10	15	pF
$Q_g$	Total Gate Charge at 10V	$V_{DS} = 480 \text{ V}$ , $I_D = 10 \text{ A}$ , $V_{GS} = 10 \text{ V}$	-	23	30	nC
$Q_{gs}$	Gate to Source Gate Charge		-	6	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge		(Note 4)	-	8	-

### Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 300 \text{ V}$ , $I_D = 10 \text{ A}$ , $V_{GS} = 10 \text{ V}$ , $R_G = 25 \Omega$	-	25	60	ns
$t_r$	Turn-On Rise Time		-	50	110	ns
$t_{d(off)}$	Turn-Off Delay Time		-	70	150	ns
$t_f$	Turn-Off Fall Time		(Note 4)	-	50	110

### Drain-Source Diode Characteristics

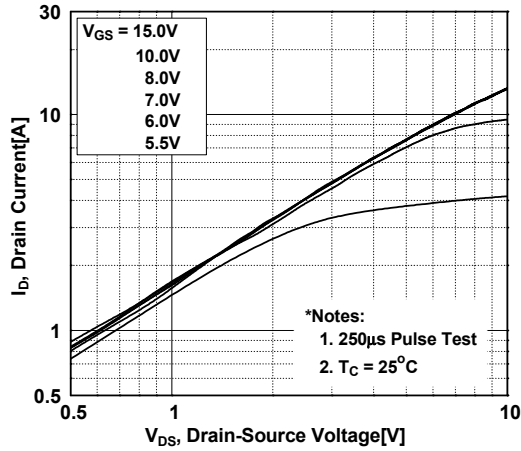
$I_S$	Maximum Continuous Drain to Source Diode Forward Current	-	-	10	A	
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	40	A	
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}$ , $I_{SD} = 10 \text{ A}$	-	-	1.4	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0 \text{ V}$ , $I_{SD} = 10 \text{ A}$ , $di_F/dt = 100 \text{ A}/\mu\text{s}$	-	300	-	ns
$Q_{rr}$	Reverse Recovery Charge		-	2.0	-	$\mu\text{C}$

#### Notes:

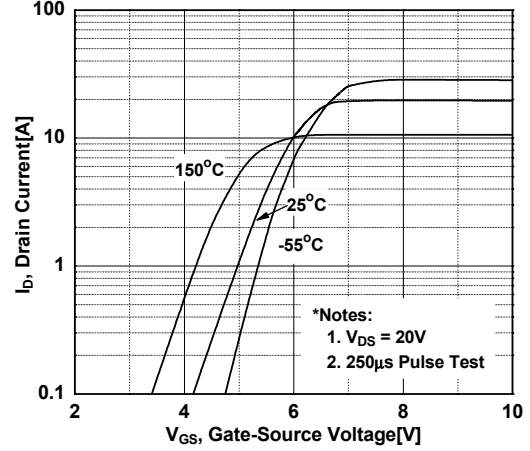
1. Repetitive rating: pulse-width limited by maximum junction temperature.
2.  $L = 11 \text{ mH}$ ,  $I_{AS} = 10 \text{ A}$ ,  $V_{DD} = 50 \text{ V}$ ,  $R_G = 25 \Omega$ , starting  $T_J = 25^\circ\text{C}$ .
3.  $I_{SD} \leq 10 \text{ A}$ ,  $di/dt \leq 200 \text{ A}/\mu\text{s}$ ,  $V_{DD} \leq BV_{DSS}$ , starting  $T_J = 25^\circ\text{C}$ .
4. Essentially independent of operating temperature typical characteristics.

## Typical Performance Characteristics

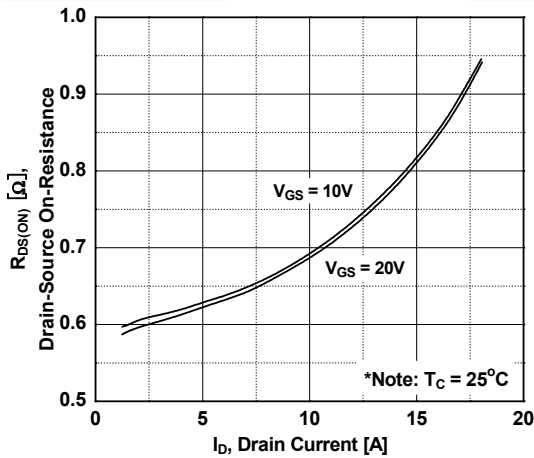
**Figure 1. On-Region Characteristics**



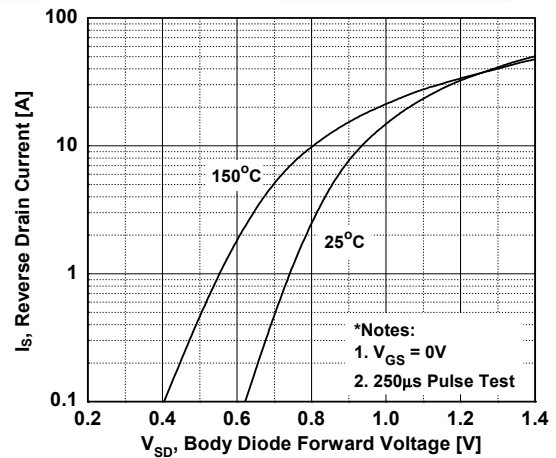
**Figure 2. Transfer Characteristics**



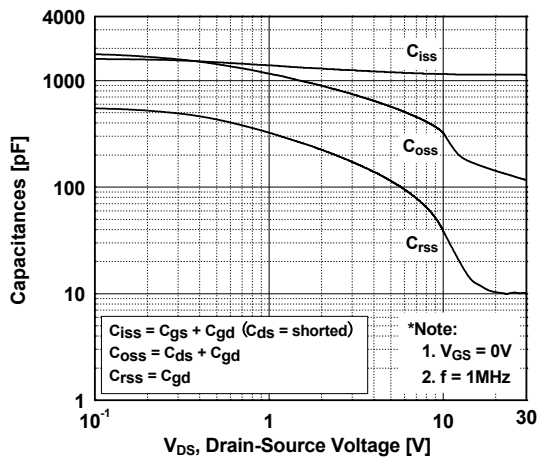
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



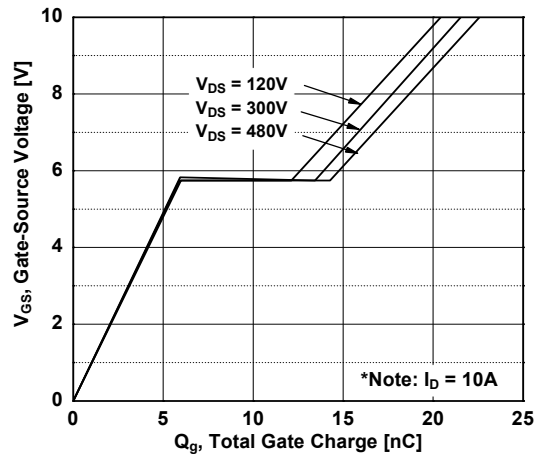
**Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature**



**Figure 5. Capacitance Characteristics**

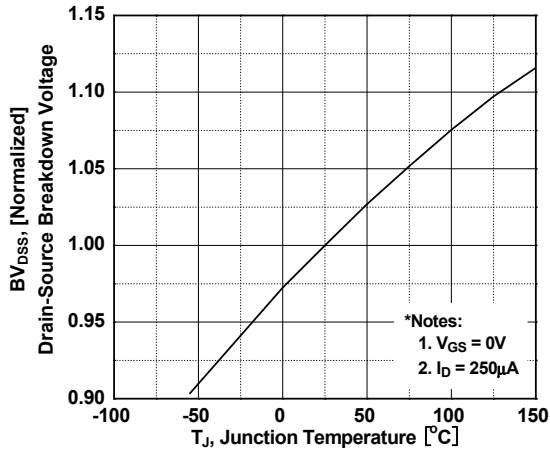


**Figure 6. Gate Charge Characteristics**

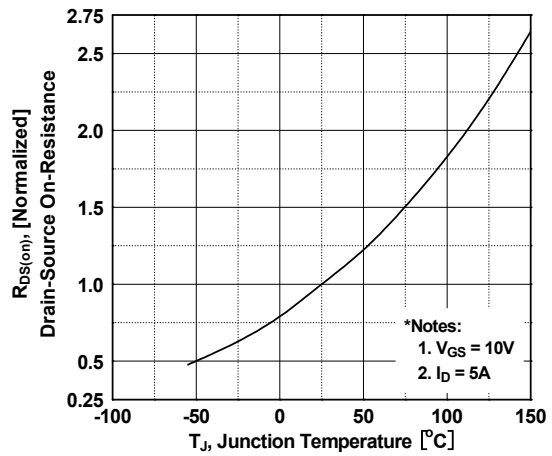


**Typical Performance Characteristics** (Continued)

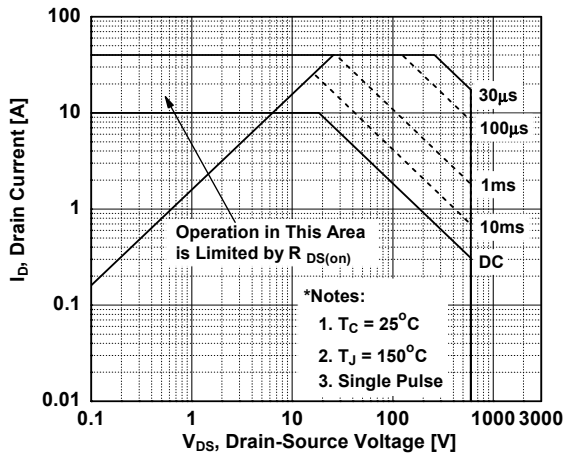
**Figure 7. Breakdown Voltage Variation vs. Temperature**



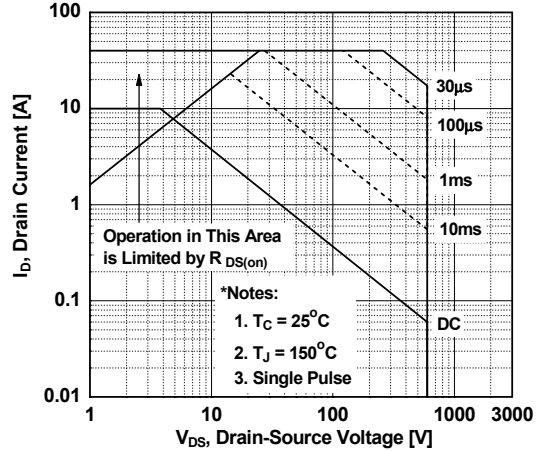
**Figure 8. On-Resistance Variation vs. Temperature**



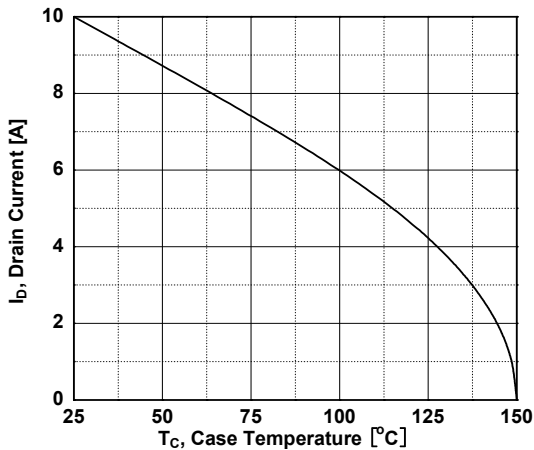
**Figure 9. Maximum Safe Operating Area - FDP10N60NZ**



**Figure 10. Maximum Safe Operating Area - FDPF10N60NZ**



**Figure 11. Maximum Drain Current vs. Case Temperature**



Typical Performance Characteristics (Continued)

Figure 12. Transient Thermal Response Curve  
- FDP10N60NZ

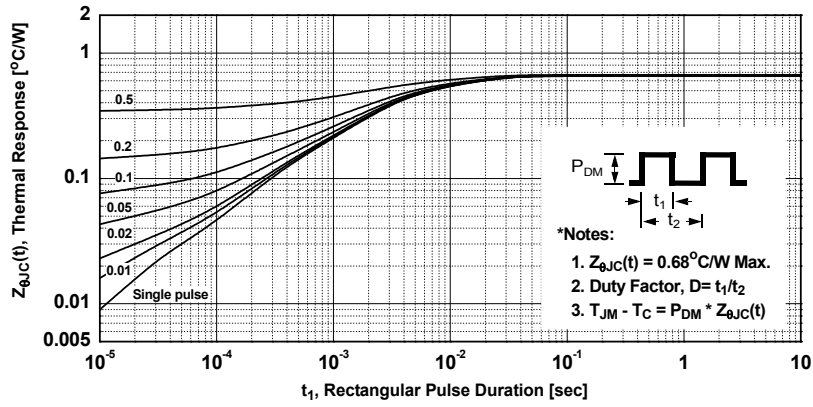


Figure 13. Transient Thermal Response Curve  
- FDPF10N60NZ

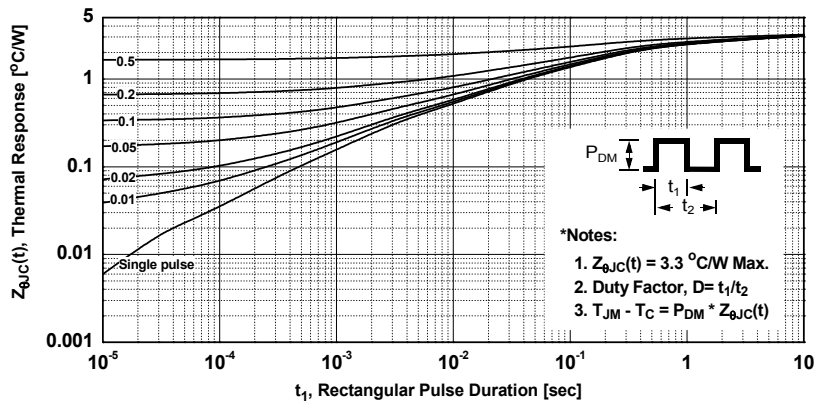




Figure 14. Gate Charge Test Circuit & Waveform



Figure 15. Resistive Switching Test Circuit & Waveforms



Figure 16. Unclamped Inductive Switching Test Circuit & Waveforms



Figure 17. Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms

## Mechanical Dimensions



**Figure 18. TO-220, Molded, 3-Lead, Jedec Variation AB**

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:

[http://www.fairchildsemi.com/package/packageDetails.html?id=PN\\_TT220-003](http://www.fairchildsemi.com/package/packageDetails.html?id=PN_TT220-003)





